

AMENDMENTS TO THE SPECIFICATION

Please substitute the following paragraph for the paragraph that begins on page 1, line 4:

CROSS REFERENCE TO RELATED APPLICATIONS

This application is a divisional application claiming priority from US Patent Application serial no. 09/455,977 filed December 6, 1999, which has issued as US Patent 6,386,251; which is a continuation of US Patent 6,030,478 (serial no. 09/021,518 filed February 10, 1998); the disclosures of which are incorporated herein by reference.

Please substitute the following paragraph for the paragraph beginning on page 9, line 7:

Referring now to Fig. 2, patch assembly 60 is then assembled to the innerliner 75 of tire ~~70~~ 71. Activating cement is first applied to second side 22 of dual cure bonding layer 20. The patch assembly is then stitched to the innerliner of the vulcanized tire and the patch assembly/tire assembly is allowed to cure for a sufficient time and temperature to form a strong bond between the tire and the patch assembly. The times and temperatures utilized for this curing may be basically the same times and temperatures as previously discussed. To ensure a strong bond, the patch assembly optionally may be clamped to the tire innerliner 75, until the curing cycle is completed.

Please substitute the following paragraph for the paragraph starting on page 9, line 16:

The electronic monitoring device is a circuit board which includes sensors and ~~optional~~ optionally, an antenna. The electronic monitoring device may include a power source or battery, although the battery may be attached to the

electronic monitoring device at a later time. In the preferred embodiment, the battery is not included as part of the electronic monitoring device. The electronic monitoring device 34 is encapsulated in a potting material 40 which solidifies into a rigid material as shown in Fig. 3. Referring to Figs. 3 and 4, the electronic monitoring device 34 is placed within a mold 40 42 having a first half 52 and a second half 54. The mold is then filled with the potting material 40 in fluid form, which fills the mold and flows around the electronic monitoring device and allowed to cure, resulting in a rigid tag. Any potting material having a Young's Modulus of at least 30,000 psi and which is capable of being molded around the electronic monitoring device without damaging any of the components of the device. Preferably, the potting material has a Young's Modulus of at least about 100,000 psi. Two preferred potting materials include epoxy and urethane. If desired, the curing of the potting material around the electronic device may be accelerated by preheating the mold to an elevated temperature which is above ambient, but below the temperature at which damage to the electronic monitoring device will occur. A preferred temperature is about 80°C. After the epoxy has been cured, the mold halves 52, 54 are separated, yielding a rigid, encapsulated tag 30. In a preferred embodiment, Fig. 5, a battery 68 which provides power to the tag 30 is attached to the tag to form a tag assembly 70. Although the battery is shown as held in position contacting the electronic monitoring device 34 by threading, any suitable means of attaching the battery to the circuit board so that the battery may be removed is acceptable. Alternate means of attaching the battery to the circuit board may include spring clips, lock pins or other hold down devices.